



U.S. Patent Application Serial No. 10/615,381
Reply to OA dated June 15, 2006

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-13 (Canceled)

Claim 14 (Previously Presented): A surface treating apparatus according to claim 21, wherein said vapor deposition controlling gas is hydrogen.

Claim 15 (Currently Amended): A surface treating apparatus according to claim 21, wherein the molar ratio of said vapor deposition controlling gas to oxygen in at least [[the]] a space between said melting/evaporating source and said work within said treating chamber can be adjusted by the feed rate of said vapor-depositing material fed from said feed reel.

Claims 16 - 20 (Canceled)

21. (Currently Amended): A surface treating apparatus comprising:
a treating chamber connected to an evacuating system;
a melting/evaporating source for melting and evaporating ~~the~~ a wire-shaped vapor-depositing material containing a vapor deposition controlling gas, disposed in the treating chamber;

a rotatable cage-shaped, work retaining member, disposed in the treating chamber, and spaced above the melting/evaporating source, for retaining a work on which the vapor depositing material is deposited; and

a supply of wire-shaped vapor-depositing material containing a predetermined amount of the vapor deposition controlling gas wound about a feed reel;

a thermal resistant protective tube disposed between the feed reel and the melting/evaporating source; and

the feed reel being mounted so as to rotate about a substantially vertical rotational axis, and
~~a horizontally disposed feed reel arranged such that the a direction of winding of the wire-shaped vapor-depositing material containing the vapor deposition controlling gas on the feed reel is perpendicular to the a direction of feeding of the wire-shaped vapor-depositing material containing the vapor deposition controlling gas to supply the wire-shaped vapor-depositing material containing the vapor deposition controlling gas to the melting/evaporating source;~~ disposed in the treating chamber below the melting/evaporating source;

such that, as the wire-shaped vapor-depositing material containing the vapor deposition controlling gas is supplied from the feed reel to the melting/evaporating source, the wire-shaped vapor-depositing material containing the vapor deposition controlling gas has a horizontally disposed lower portion, a vertically disposed intermediate portion and a horizontally disposed upper portion, and the wire-shaped vapor-depositing material containing the vapor deposition controlling gas is

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protected by the thermal resistant protective tube between the feed reel and the melting/evaporating source.